

Device and method for separating a temporarily bonded substrate stack

Abstract

The present invention relates to a method for separating a temporarily bonded substrate stack (23) by bombardment of a joining layer (25) of the substrate stack (23) by means of laser beams (16, 16') emitted by a laser (5), characterised in that laser beams (16, 16', 16r) of the laser (5) reflected and/or transmitted at the temporarily bonded substrate stack (23) are detected during the bombardment of the joining layer (25) with the laser beams (16, 16'). Furthermore, the invention relates to a corresponding device.

Figure 2